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APPLICATION NO.	F	ILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO
09/687,048		10/13/2000	Tae Heon Lee	AMKOR-052A 1120	
7663	7590	10/22/2003	•	EXAMINER	
STETINA 75 ENTERI	=	A GARRED & BRU	NGUYEN, DILINH P		
ALISO VIE				ART UNIT PAPER NUMBER	
	•			2814	

DATE MAILED: 10/22/2003

Please find below and/or attached an Office communication concerning this application or proceeding.

•	Application No.	Applicant(s)	Applicant(s)						
• •	09/687,048	LEE ET AL.							
Office Action Summary	Examiner	Art Unit	1						
	DiLinh Nguyen	2814	AW						
The MAILING DATE of this communication appears on the cover sheet with the correspondence address Period for Reply									
A SHORTENED STATUTORY PERIOD FOR REPL THE MAILING DATE OF THIS COMMUNICATION.  - Extensions of time may be available under the provisions of 37 CFR 1.7 after SIX (6) MONTHS from the mailing date of this communication.  - If the period for reply specified above is less than thirty (30) days, a rep If NO period for reply is specified above, the maximum statutory period - Failure to reply within the set or extended period for reply will, by statute - Any reply received by the Office later than three months after the mailin earned patent term adjustment. See 37 CFR 1.704(b).  Status	136(a). In no event, however, may a ly within the statutory minimum of th will apply and will expire SIX (6) MC e, cause the application to become	a reply be timely filed  nirty (30) days will be considered time  DNTHS from the mailing date of this of  ABANDONED (35 U.S.C. § 133).							
1) Responsive to communication(s) filed on 26	September 2003 .								
2a)☐ This action is <b>FINAL</b> . 2b)⊠ The	nis action is non-final.								
3) Since this application is in condition for allow closed in accordance with the practice under Disposition of Claims			ne merits is						
4) Claim(s) 16-35 is/are pending in the application	on.								
4a) Of the above claim(s) is/are withdra	wn from consideration.								
5) Claim(s) is/are allowed.		,							
6)⊠ Claim(s) <u>16-35</u> is/are rejected.									
7) Claim(s) is/are objected to.									
8) Claim(s) are subject to restriction and/o	or election requirement.	•							
Application Papers									
9) The specification is objected to by the Examine									
10)☐ The drawing(s) filed on is/are: a)☐ acce									
Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).  11) The proposed drawing correction filed on is: a) approved b) disapproved by the Examiner.									
If approved, corrected drawings are required in re		disapproved by the Examin	iei.						
12) The oath or declaration is objected to by the Ex	•	•							
Priority under 35 U.S.C. §§ 119 and 120	(Cirmion)								
13) Acknowledgment is made of a claim for foreig	n priority under 35 U.S.C.	8 119(a)-(d) or (f)							
a)⊠ All b)□ Some * c)□ None of:	in priority under 00 0.0.0	. 3 170(4) (4) 51 (1).							
1.⊠ Certified copies of the priority document	ts have been received.								
2. Certified copies of the priority document		Application No							
3. Copies of the certified copies of the prication from the International But See the attached detailed Office action for a list	ority documents have bee ureau (PCT Rule 17.2(a))	n received in this National	Stage						
14) Acknowledgment is made of a claim for domest	ic priority under 35 U.S.C	c. § 119(e) (to a provisiona	l application).						
a) ☐ The translation of the foreign language pro 15)☐ Acknowledgment is made of a claim for domes	• •								
Attachment(s)									
1) Notice of References Cited (PTO-892) 2) Notice of Draftsperson's Patent Drawing Review (PTO-948) 3) Information Disclosure Statement(s) (PTO-1449) Paper No(s)	5) Notice of	w Summary (PTO-413) Paper No of Informal Patent Application (PT							

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## **DETAILED ACTION**

## Claim Rejections - 35 USC § 103

- 1. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
  - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.
- 2. Claims 16-35 are rejected under 35 U.S.C. 103(a) as being unpatentable over AAPA (figs. 1-2) in view of Shin et al. (U.S. Pat. 5866939).
  - Regarding claims 16, 25 and 31, AAPA (figs. 1-3) disclose a semiconductor device comprising:
    - a lead frame 100 having:
- a chip paddle 110 defining opposed top and bottom surfaces and a plurality of sides and corners; and
- a plurality of leads 130 extending along at least one of the sides of the chip paddle in spaced relation thereto, each of the leads defining opposed top and bottom surfaces:

a semiconductor chip 105 mounted to the top surface of the chip paddle and electrically connected to at least one of the leads; and

an encapsulation material 10 covering the leadframe and the semiconductor chip such that the bottom surfaces of the leads are exposed in the encapsulation material;

the leads being configured such that the bottom surfaces thereof which are exposed in the encapsulation material.

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AAPA (figs. 1-3) fail to disclose the leads are of at least two different lengths.

Shin et al. disclose a semiconductor device (figs. 5A, 6A and 7A) comprising:

an encapsulation material (column 6, lines 55-60) covering the leadframe and the semiconductor chip such that the bottom surfaces of the leads 2, which are of at least two different lengths, are exposed in the encapsulation material. Therefore, it would have been obvious to one having ordinary skill in the art at the time the invention was made to modify the device of AAPA (figs. 1-2) to provide smooth signal transmission can be run at a high speed and improve the reliability of the package, as shown by Shin et al.

- Regarding claims 17, 26 and 32, Shin et al. disclose the leads are segregated into multiple sets which extend along respective ones of the sides of the chip paddle in spaced relation thereto (fig. 5b).
- Regarding claims 18, 27 and 33, Shin et al. disclose the leads of each set include
  at least two outer leads and at least one inner lead disposed between the outer
  leads, the bottom surfaces of the outer leads each being of a first length and the
  bottom surface of the inner lead being of a second length which is unequal to the
  first length.
- Regarding claims 19, 28 and 34, Shin et al. disclose the first length of the bottom surface of each of the outer leads exceeds the second length of the bottom surface of the inner lead.

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- Regarding claims 20, 29 and 35, it would have been obvious to form the first length of the bottom surface of each of the outer leads is less than the second length of the bottom surface of the inner lead.
- Regarding claim 21, AAPA (fig. 2) discloses wherein the bottom surface of the chip paddle is exposed in the encapsulation material.
- Regarding claims 22 and 30, AAPA (fig. 2) discloses the encapsulation material 10 defines a generally planar bottom surface; the bottom surface of the chip paddle is generally planar and substantially flush with the bottom surface of the encapsulation material; and the bottom surfaces of the leads are each generally planar and substantially flush with the bottom surface of the encapsulation material.
- Regarding claims 23-24, AAPA (figs. 1 and 3) discloses the leadframe further
  comprises at least one tie bar 150 attached to and extending from at least one of
  the corners of the chip paddle, the tie bar defining opposed top and bottom
  surfaces, and wherein the bottom surface of the at least one tie bar is exposed in
  the encapsulation material.

## Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to DiLinh Nguyen whose telephone number is (703) 305-6983. The examiner can normally be reached on 8:00AM - 6:00PM (M-F).

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Wael Fahmy can be reached on (703) 308-4918. The fax phone numbers

for the organization where this application or proceeding is assigned are (703) 308-7722 for regular communications and (703) 308-7724 for After Final communications.

Any inquiry of a general nature or relating to the status of this application or proceeding should be directed to the receptionist whose telephone number is (703) 308-0956.

DLN October 17, 2003

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